ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ous Materia	ials and Mfg Information			
Supplier	r Information														
Company name*			Company unique ID			ī	Unique ID Authority					Response Date*			
onsemi											2023-06-08				
Contact N	lame	Title - Contact				Phone - Contact*					Email - Contact*				
Product-l	Env-Stewards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
uthorize	d Representative*	Title - Representative			]	Phone - Representative*				Email - Representative*					
Product-l	Env-Stewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Date Version Manufacturing S		ing Site	V	eight*	UOM	Unit Type		
		FDMF3030 I		DrMOS Module		2023-06-08			PBB		1	34.314	mg	Each	
Manufa	cturing Proccess Inform	nation													
	Terminal Plating / Grid Array Material T			Cerminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Tempera		ture Max Time at Peak Tempo		Temperatu	re Num	ber of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy			1			260		C	30		second	s <b>3</b>			
Comments	3														
evel 1 - m	aximum time at peak temper	ature during sol	dering is 10-3	0 seconds											
or more	information regarding materi	ial composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	19.6	mg	Supplier	Zinc (Zn)	7440-66-6		0.0235	mg
			Supplier	Iron (Fe)	7439-89-6		0.4704	mg
			Supplier	Copper (Cu)	7440-50-8		19.0904	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0157	mg
Die	0.096	mg	Supplier	Silicon (Si)	7440-21-3		0.096	mg
Die Attach Solder	5.101	mg	Supplier	Silver (Ag)	7440-22-4		0.1275	mg
			A	Lead (Pb)	7439-92-1	7a	4.7184	mg
			Supplier	Tin (Sn)	7440-31-5		0.2551	mg
Lead Frame	44.201	mg	Supplier	Silver (Ag)	7440-22-4		0.054	mg
			Supplier	Zinc (Zn)	7440-66-6		0.049	mg
			Supplier	Iron (Fe)	7439-89-6		0.998	mg
			Supplier	Copper (Cu)	7440-50-8		43.1	mg
Mold Compound-Black	63.216	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		3.79	mg
			Supplier	Carbon Black (C)	1333-86-4		0.316	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		56.9	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.21	mg
Plating	2.0	mg	Supplier	Tin (Sn)	7440-31-5		2	mg
Wire Bond - Au	0.1	mg	Supplier	Gold (Au)	7440-57-5		0.1	mg